Product Change Notification: JPZA-22XBMO863

Date:

02-Oct-2026

Product Category:

16-Bit Microcontrollers, 32-Bit Microcontrollers, 8-Bit Microcontrollers, Digital Signal Controllers

Notification Subject:

CCB 8433 Initial Notice: Qualification of G630AY as an additional mold compound for selected dsPIC33FJ64XX, PIC24HJ256GXX, dsPIC33FJ12XX, PIC32MX340FXX, PIC32MX320FXX, PIC18F67J10XX, PIC18F66J15XX, PIC18F67J11XX, PIC18F66J16XX, PIC18F66J11XX, PIC18F65J10XX, MTR6618, dsPIC33FJ32XX, dsPIC33FJ25XX, PIC24HJ64GPXX, PIC24HJ128GXX, PIC24FJ256GXX, PIC24FJ96GAXX, PIC24FJ128GXX, PIC24FJ64GBXX, PIC18F66J65XX, PIC24FJ64GAXX, PIC18F63J90XX, MTR6853, PIC18F64J90XX, PIC18F63J11XX, PIC24FJ192GXX, PIC32MX440FXX, PIC32MX420FXX, PIC18F64J11XX, PIC18F66J90XX, PIC18F66J93XX, PIC18F67J90XX, PIC18F67J93XX, PIC18F65J90XX, PIC18F67J50XX, PIC18F66J55XX, PIC18F65J11XX, PIC18F67J60XX, PIC18F66J50XX, PIC18F65J50XX, and PIC18F66J60XX device families available in 64L TQFP (10x10x1mm) package at MTAI assembly site.

Affected CPNs:

JPZA-22XBMO863_Affected_CPN_10022026.pdf
JPZA-22XBMO863_Affected_CPN_10022026.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of G630AY as an additional mold compound for selected dsPIC33FJ64XX, PIC24HJ256GXX, dsPIC33FJ12XX, PIC32MX340FXX, PIC32MX320FXX, PIC18F67J10XX, PIC18F66J15XX, PIC18F67J11XX, PIC18F66J16XX, PIC18F66J11XX, PIC18F65J10XX, MTR6618, dsPIC33FJ32XX, dsPIC33FJ25XX, PIC24HJ64GPXX, PIC24HJ128GXX, PIC24FJ256GXX, PIC24FJ96GAXX, PIC24FJ128GXX, PIC24FJ64GBXX, PIC18F66J65XX, PIC24FJ64GAXX, PIC18F63J90XX, MTR6853, PIC18F64J90XX, PIC18F63J11XX, PIC24FJ192GXX, PIC32MX440FXX, PIC32MX420FXX, PIC18F64J11XX,

PIC18F66J90XX, PIC18F66J93XX, PIC18F67J90XX, PIC18F67J93XX, PIC18F65J90XX, PIC18F67J50XX, PIC18F66J55XX, PIC18F65J11XX, PIC18F67J60XX, PIC18F66J50XX, PIC18F65J50XX, and PIC18F66J60XX device families available in 64L TQFP (10x10x1mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	**Post Change**		**Change**
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)		No
Wire Material	CuPdAu	CuPdAu		No
Die Attach Material	QMI519 (PFAS free)	QMI519 (PFAS free)		No
Molding Compound Material	G700HA	G700HA	G630AY	Yes
Lead-Frame Material	C7025	C7025		No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying G630AY as an additional mold compound at MTAI assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: October 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	October 2026				
Work Week	40	41	42	43	44
Initial PCN Issue Date	X				
Qual Report Availability		X			
Final PCN Issue Date		X			

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: October 02, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_JPZA-22XBMO863-Qualification Plan.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

PIC32MX320F032HT-40V/PT

PIC32MX340F512HT-80V/PT

PIC32MX340F128HT-80V/PT

PIC32MX340F256HT-80I/PT

PIC32MX320F128HT-80I/PT

PIC32MX320F064HT-40I/PT

PIC32MX320F064HT-80I/PT

PIC24HJ256GP206AT-I/PT027

PIC24HJ256GP206AT-I/PT

DSPIC33FJ256GP506AT-I/PT

PIC24HJ256GP206AT-E/PT

PIC32MX440F256H-80I/PT

PIC32MX440F512H-80I/PT

PIC18F67J90-I/PT

PIC18F67J93-I/PT

PIC18F67J90T-I/PT

PIC18F65J90-I/PT

PIC18F65J90-I/PTREL

PIC24FJ128GA006T-I/PT

PIC24FJ64GB106-I/PT

PIC24FJ96GA006T-I/PTV01

PIC24FJ128GA006T-I/PTV04

PIC24FJ64GA106-I/PTC23

PIC24FJ64GA106T-I/PT

PIC24FJ192GB106-I/PT

PIC18F66J90-I/PT

PIC18F66J93-I/PT

PIC18F66J90T-I/PT

PIC24HJ128GP206A-E/PT

PIC24HJ128GP306A-E/PT

PIC24HJ128GP506A-E/PT

DSPIC33FJ64GS606-E/PT

DSPIC33FJ64GS606-I/PTD22

DSPIC33FJ64GS606-I/PT

DSPIC33FJ64GS606T-I/PT

DSPIC33FJ64GS606T-E/PTD22

PIC18F65J90T-I/PT

PIC18F67J50-I/PT

PIC18F67J50T-I/PT024

PIC18F67J50T-I/PT

PIC18F66J55-I/PT

PIC18F65J11-I/PT

PIC18F65J11T-I/PT

PIC18F66J16-I/PT

PIC18F67J60-I/PT

PIC18F67J60-I/PTREL

PIC18F67J60T-I/PT

DSPIC33FJ64GP206-I/PT

DSPIC33FJ64GP306-I/PT

DSPIC33FJ64GP706-I/PT

PIC24FJ64GA006T-I/PT037

PIC24FJ64GA006T-I/PT039

PIC24FJ64GA006T-I/PT040

DSPIC33FJ128MC706-I/PT

DSPIC33FJ64MC506T-I/PT

DSPIC33FJ64MC706T-I/PT

DSPIC33FJ128MC706T-I/PT

PIC24HJ64GP206-I/PT

PIC24FJ64GA006T-I/PTC03

PIC24FJ64GA006T-I/PTC08

PIC24FJ64GA006T-I/PT

PIC24HJ128GP506A-H/PT

DSPIC33FJ32GS606-50I/PT

DSPIC33FJ128GP306T-I/PT

DSPIC33FJ128GP706T-I/PT

DSPIC33FJ128GP206A-E/PT

DSPIC33FJ128GP306A-E/PT

DSPIC33FJ128GP706A-E/PT

DSPIC33FJ64GP306A-I/PT037

DSPIC33FJ64GP206A-I/PT

DSPIC33FJ64GP306A-I/PT

DSPIC33FJ64GP706A-I/PT

DSPIC33FJ128GP206A-I/PT

DSPIC33FJ128GP306A-I/PT

DSPIC33FJ128GP706A-I/PT

DSPIC33FJ64GP206AT-I/PT032

DSPIC33FJ64GP206AT-I/PT

DSPIC33FJ64GP706AT-I/PT

DSPIC33FJ128GP206AT-I/PT

DSPIC33FJ128GP306AT-I/PT

DSPIC33FJ128GP306AT-E/PT

PIC18F66J10-I/PT

PIC18F66J10T-I/PT

PIC18F66J10T-I/PTC01

PIC18F65J15-I/PT

PIC18F67J10T-I/PT020

PIC18F67J10T-I/PT

PIC18F66J15-I/PT

PIC18F66J15T-I/PT

PIC18F67J11-I/PTC03

PIC18F67J11T-I/PTC03

DSPIC33FJ64GS406-50I/PT

DSPIC33FJ64GS406T-50I/PT

PIC24HJ256GP206A-E/PT

DSPIC33FJ256GP506A-E/PT

PIC24HJ256GP206A-I/PT

DSPIC33FJ256GP506A-I/PT

PIC24HJ64GP206A-I/PT

PIC24FJ64GA106-I/PT

DSPIC33FJ128GP206-I/PT

DSPIC33FJ128GP306-I/PT

DSPIC33FJ128GP706-I/PT

DSPIC33FJ256GP506-I/PT

DSPIC33FJ64GP206T-I/PT

DSPIC33FJ64GP306T-I/PT

DSPIC33FJ64GP706T-I/PT

PIC32MX320F064HT-40V/PT

PIC32MX320F064HT-80V/PT

DSPIC33FJ128MC506AT-I/PT

DSPIC33FJ128MC706AT-I/PT

DSPIC33FJ64MC506AT-E/PT

DSPIC33FJ128MC706AT-E/PT

PIC24HJ64GP506-I/PT

PIC18F66J50-I/PT

PIC18F66J50T-I/PT

PIC18F65J50-I/PT

PIC24FJ128GA106-I/PT041

PIC24FJ128GA106-I/PTA5

PIC24FJ128GA106-I/PT

PIC24FJ128GA106-I/PTC13

PIC24FJ128GA106T-I/PT041

PIC24FJ128GA106T-I/PTA5

PIC24FJ128GA106T-I/PT

PIC24FJ128GA106T-I/PTC13

PIC24FJ192GA106-E/PT

PIC24FJ192GA106-I/PTC22

PIC24FJ192GA106-I/PT

PIC24FJ192GA106T-I/PT

PIC24FJ128GB106-I/PT

PIC24FJ128GB106T-I/PT031

PIC24FJ128GB106T-I/PT032

PIC24FJ128GB106T-I/PT

DSPIC33FJ32GS406T-I/PT

DSPIC33FJ32GS406T-E/PT

DSPIC33FJ32GS606T-E/PT

DSPIC33FJ32GS406-50I/PT

DSPIC33FJ32GS406T-50I/PT

DSPIC33FJ128MC506A-E/PT

DSPIC33FJ128MC706A-E/PT

DSPIC33FJ64MC506A-I/PT

DSPIC33FJ64MC706A-I/PT

DSPIC33FJ128MC506A-I/PT

DSPIC33FJ128MC706A-I/PT

DSPIC33FJ64MC506AT-I/PT022

DSPIC33FJ64MC506AT-I/PT023

DSPIC33FJ64MC506AT-I/PT025

DSPIC33FJ64MC506AT-I/PT026

DSPIC33FJ64MC506AT-I/PT027

DSPIC33FJ64MC506AT-I/PT029

DSPIC33FJ64MC506AT-I/PT034

DSPIC33FJ128MC506AT-I/PT061

PIC32MX420F032HT-40I/PT

PIC24FJ64GA106-E/PT

PIC24HJ64GP506A-I/PT

PIC32MX440F128H-80I/PT

PIC32MX420F032H-40I/PT

PIC32MX440F256H-80V/PT

PIC32MX440F512H-80V/PT

PIC32MX440F128H-80V/PT

PIC32MX420F032H-40V/PT

PIC32MX440F256HT-80V/PT

PIC32MX320F064H-80I/PT

PIC32MX320F032H-40I/PT

PIC32MX340F512H-80I/PT

PIC32MX340F128H-80I/PT

PIC32MX340F256H-80V/PT

PIC32MX320F128H-80V/PT

PIC32MX320F064H-40V/PT

PIC32MX320F064H-80V/PT

PIC32MX320F032H-40V/PT

PIC32MX340F512H-80V/PT

PIC32MX340F128H-80V/PT

PIC32MX340F256HT-80V/PT

PIC32MX320F128HT-80V/PT

DSPIC33FJ128GP206T-I/PT

DSPIC33FJ32GS606T-50I/PT

PIC24FJ256GA106T-I/PT037

PIC24FJ256GA106T-I/PT

PIC24FJ96GA006-I/PT

PIC24FJ96GA006T-I/PT

PIC32MX320F032HT-40I/PT

PIC32MX340F512HT-80I/PT

PIC32MX340F128HT-80I/PT

DSPIC33FJ64GS606T-50I/PT

PIC18F64J11-I/PT

PIC18F64J11T-I/PT

DSPIC33FJ32GS606-E/PT

DSPIC33FJ32GS606-I/PTD23

DSPIC33FJ32GS606-I/PT

DSPIC33FJ32GS606T-I/PTC01

PIC18F63J90-I/PT

PIC18F66J11-I/PTC01

MTR6853-I/PT

PIC32MX440F128HT-80I/PT

DSPIC33FJ64MC506-I/PT

PIC18F65J10T-I/PT

PIC18F67J11-I/PT

MTR6618-I/PT

PIC18F67J11-I/PTC04

PIC18F67J11-I/PTC06

PIC18F67J11T-I/PT

PIC18F67J11T-I/PTC06

DSPIC33FJ64GS406-E/PT

DSPIC33FJ64GS406-I/PT

DSPIC33FJ64GS406T-I/PT

DSPIC33FJ64GS406T-E/PT

DSPIC33FJ32GS406-E/PT

DSPIC33FJ32GS406-I/PT

DSPIC33FJ32GS606T-I/PTC04

DSPIC33FJ32GS606T-I/PTD23

DSPIC33FJ32GS606T-I/PT

PIC24FJ128GA006-I/PT

PIC24FJ128GA006T-I/PT033

PIC24FJ128GA006T-I/PTC2

PIC24HJ128GP206A-I/PT

PIC24HJ128GP306A-I/PT

PIC24HJ128GP506A-I/PT

PIC24HJ128GP306AT-I/PT060

PIC24HJ64GP206AT-I/PT

PIC24HJ64GP506AT-I/PT

PIC24HJ128GP206AT-I/PT

PIC24HJ128GP306AT-I/PT

PIC24HJ128GP506AT-I/PT

PIC24HJ128GP206AT-E/PT

PIC24HJ128GP306AT-E/PT

PIC24FJ64GB106T-I/PT

DSPIC33FJ128MC506A-H/PT

DSPIC33FJ128MC706A-H/PT

PIC18F66J65-I/PT

PIC24HJ256GP206A-H/PT

PIC24FJ64GA006-I/PTC03

PIC24FJ64GA006-I/PT

PIC24FJ64GA006T-I/PT032

PIC18F64J90-I/PT

PIC24FJ128GA006-I/PTC2

DSPIC33FJ64MC506AT-I/PT

DSPIC33FJ64MC706AT-I/PT

PIC24HJ128GP206-I/PT

PIC24HJ128GP306-I/PT

PIC24HJ128GP506-I/PT

DSPIC33FJ64GS606T-I/PTD22

PIC24HJ256GP206T-I/PT035

DSPIC33FJ64MC506T-I/PTC21

DSPIC33FJ128GP706AT-I/PT

DSPIC33FJ64MC506AT-I/PTC27

PIC32MX340F256H-80I/PT

PIC32MX320F128H-80I/PT

PIC32MX320F064H-40I/PT

DSPIC33FJ64GS606T-E/PT

PIC18F67J10-I/PT

PIC18F67J10-I/PTC03

PIC18F67J10-I/PTREL

PIC18F67J10-I/PTXXX

DSPIC33FJ64MC706-I/PT

DSPIC33FJ128MC506-I/PT

PIC24HJ256GP206-I/PT

PIC24HJ64GP206T-I/PT

PIC24HJ64GP506T-I/PT

PIC24HJ128GP206T-I/PT

PIC24HJ128GP506T-I/PT

PIC24HJ256GP206T-I/PT

PIC24HJ64GP206A-E/PT

PIC24FJ128GA106-I/PT026

PIC24FJ128GA106-I/PT038

PIC18F66J60-I/PT

DSPIC33FJ128MC706A-E/PTC01

DSPIC33FJ64MC506A-E/PT

DSPIC33FJ64MC706A-E/PT

PIC24FJ64GA006T-I/PT036

PIC24FJ128GB106-I/PTC06

DSPIC33FJ256GP506T-I/PT

PIC18F65J15T-I/PT

DSPIC33FJ128GP706A-H/PT

PIC24FJ256GA106-E/PT

PIC24FJ256GA106-I/PT031

PIC24FJ256GA106-I/PT

PIC18F64J90T-I/PT

PIC18F63J11-I/PT

PIC24FJ256GB106-I/PT

PIC24FJ256GB106T-I/PT

PIC24FJ128GA106-E/PT

PIC24HJ128GP506AT-E/PT

DSPIC33FJ64GP206A-E/PT

DSPIC33FJ64GP706A-E/PT

DSPIC33FJ256GP506AT-E/PT

DSPIC33FJ64MC506-I/PTC21

DSPIC33FJ64GS606-50I/PT

DSPIC33FJ64GS606T-50I/PTC01

PIC32MX440F512HT-80V/PT

PIC32MX440F128HT-80V/PT

PIC32MX420F032HT-40V/PT

PIC32MX440F256HT-80I/PT

PIC32MX440F512HT-80I/PT

PIC18F66J16T-I/PT

PIC18F66J11-I/PT

PIC18F66J11T-I/PT

PIC18F65J10-I/PT

QUALIFICATION PLAN SUMMARY

PCN#: JPZA-22XBMO863

DATE:
September 28, 2026

Qualification of G630AY as an additional mold compound for selected dsPIC33FJ64XX, PIC24HJ256GXX, dsPIC33FJ12XX, PIC32MX340FXX, PIC32MX320FXX, PIC18F67J10XX, PIC18F66J15XX, PIC18F67J11XX, PIC18F66J16XX, PIC18F66J11XX, PIC18F65J10XX, MTR6618, dsPIC33FJ32XX, dsPIC33FJ25XX, PIC24HJ64GPXX, PIC24HJ128GXX, PIC24FJ256GXX, PIC24FJ96GAXX, PIC24FJ128GXX, PIC24FJ64GBXX, PIC18F66J65XX, PIC24FJ64GAXX, PIC18F63J90XX, MTR6853, PIC18F64J90XX, PIC18F63J11XX, PIC24FJ192GXX, PIC32MX440FXX, PIC32MX420FXX, PIC18F64J11XX, PIC18F66J90XX, PIC18F66J93XX, PIC18F67J90XX, PIC18F67J93XX, PIC18F65J90XX, PIC18F67J50XX, PIC18F66J55XX, PIC18F65J11XX, PIC18F67J60XX, PIC18F66J50XX, PIC18F65J50XX, and PIC18F66J60XX device families available in 64L TQFP (10x10x1mm) package at MTAI assembly site.

Purpose: Qualification of G630AY as an additional mold compound for selected dsPIC33FJ64XX, PIC24HJ256GXX, dsPIC33FJ12XX, PIC32MX340FXX, PIC32MX320FXX, PIC18F67J10XX, PIC18F66J15XX, PIC18F67J11XX, PIC18F66J16XX, PIC18F66J11XX, PIC18F65J10XX, MTR6618, dsPIC33FJ32XX, dsPIC33FJ25XX, PIC24HJ64GPXX, PIC24HJ128GXX, PIC24FJ256GXX, PIC24FJ96GAXX, PIC24FJ128GXX, PIC24FJ64GBXX, PIC18F66J65XX, PIC24FJ64GAXX, PIC18F63J90XX, MTR6853, PIC18F64J90XX, PIC18F63J11XX, PIC24FJ192GXX, PIC32MX440FXX, PIC32MX420FXX, PIC18F64J11XX, PIC18F66J90XX, PIC18F66J93XX, PIC18F67J90XX, PIC18F67J93XX, PIC18F65J90XX, PIC18F67J50XX, PIC18F66J55XX, PIC18F65J11XX, PIC18F67J60XX, PIC18F66J50XX, PIC18F65J50XX, and PIC18F66J60XX device families available in 64L TQFP (10x10x1mm) package at MTAI assembly site.

CCB No.: 8433

Misc.	Assembly site	MTAI
	BD Number	BD-004510/01
	MP Code (MPC)	YGAW14V2XADA
	Part Number (CPN)	PIC24HJ64GP206A-E/PT
	MSL information	MSL-1
	Assembly Shipping Media (T/R, Tube/Tray)	Tray
	Base Quantity Multiple (BQM)	160
	Reliability Site	MTAI
Lead-Frame	Paddle size	275 x 275
	Material	C7025
	DAP Surface Prep	Bare Cu
	Treatment	Roughened
	Process	Stamped
	Lead-lock	No
	Part Number	10106403
	Lead Plating	Matte Tin
Bond Wire	Material	CuPdAu
	Wire Diameter	0.8 mil
Die Attach	Part Number	QMI519 (PFAS free)
	Conductive	Yes
MC	Part Number	G630AY
PKG	Package Type	TQFP
	Pin/Ball Count	64
	PKG width/size	10x10

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Special Instructions
Standard Pb-free Solderability	J-STD-002E ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5	MTAI	MTAI	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	MTAI	MTAI	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	MTAI	MTAI	30 bonds from a min. 5 devices.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	MTAI	MTAI	
HTSL (High Temp Storage Life)	JESD22-A103. +175°C for 504 hours or +150°C for 1008 hrs. Electrical test pre and post stress at +25°C and hot temp.	45	5	3 (Cu wire qual)	150 (Cu wire qual)	0	10	MTAI	MTAI	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. (MSL1/260)	231	15	3	738	0	15	MTAI	MTAI	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A110. +130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours. Electrical test pre and post stress at +25°C and hot temp.	77	5	3	246	0	10	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A118. +130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at +25°C	77	5	3	246	0	10	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.